



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Tae Heon Lee et al.	)	Confirmation No.	8528
Serial No.:	10/763,859	)	Art Unit:	2814
Filed:	01/23/2004	)	Examiner:	Cao, Phat X.
For:	Semiconductor Package Having Reduced Thickness	)		

**RESPONSE TO OFFICE ACTION**

Mail Stop AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

Applicant hereby responds to the Office Action mailed November 28, 2005 in relation to the above-identified patent application as follows:

*Remarks* begin on page 2 of this paper.